Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
J	726	"118"/\$.ccls. and (thickness) and (spin near3 (coat or coating))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/01 16:17
L2	15	"118"/\$.ccls. and (thickness near4 sensor) and (spin near3 (coat or coating))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/01 17:12
L3	2	("6680078").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 19:41
L4	2	("20030012868").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 17:35
L5	27	"427"/\$.ccls. and (thickness near4 sensor) and (spin near3 (coat or coating))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/01 18:37
L6	38	"118"/\$.ccls. and (thickness near4 sensor) and (semiconductor near3 wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/01 17:12
L7	29	"427"/\$.ccls. and (thickness near4 sensor) and (semiconductor near3 wafer)		OR	ON	2005/05/01 17:14
L8	20	"118"/\$.ccls. and subram\$.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/01 17:14
L9	0	("2003/0068430").URPN.	USPAT	OR	ON	2005/05/01 17:18

L10	457	(118/688).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 17:35
L 11	479	(118/665).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 17:36
L12	397	(118/679).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 18:36
L13	1454	(118/712).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 17:36
L14	221	(118/713).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 17:36
L15	1	("5393624").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/01 17:55
L16	10	("3707760" "4121936" "4285433" "4500615" "4738910" "4778326" "4841156" "4851311" "4977330" "5220405").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/01 17:56
L17	55	("5393624").URPN.	USPAT	OR	ON	2005/05/01 17:57
L18	1	("5393624").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/01 18:11
L19		("5818596").URPN.	USPAT	OR	ON	2005/05/01 18:11
L20	103	(118/677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 18:36

L21	154	(118/676).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 18:37
L22	472	(118/321).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 18:37
L23	970	(118/320).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/01 18:37
1.24	985	semiconductor and (thickness near4 (measuring or measure or measurement)) and (spin near3 (coat or coating))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/01 18:38
L25	362	semiconductor and (thickness near4 (measuring or measure or measurement)) and (spin near3 (coat or coating)) and (sensor or detector)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/01 18:53
L26	57	semiconductor and ((thickness near4 (measuring or measure or measurement)) near25 (sensor or detector)) and (spin near3 (coat or coating))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/01 18:53
L27	27	(("4,906,844") or ("5,131,752") or ("5,174,931") or ("5,252,414") or ("5,337,150") or ("5,602,399") or ("5,719,440") or ("5,783,342") or ("6,251,488") or ("6,252,670") or ("6,259,962") or ("6,268,584") or ("6,305,769") or ("6,326,698") or ("6,391,251") or ("6,426,840") or ("6,482,576") or ("6,492,651") or ("6,524,346") or ("6,529,027") or ("6,532,394") or ("6,537,482") or ("6,544,465") or ("6,544,902") or ("6,549,821") or ("6,563,578") or ("6,607,689")).PN.	USPAT; USOCR	OR	OFF	2005/05/01 20:05

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L28	14	(("20020171177") or	US-PGPUB	OR	OFF	2005/05/01 20:02
,	1	("20020195748") or				
,		("20030003179") or				
		("20030003180") or				
		("20030003380") or		·		
,		("20030003405") or				
,		("20030043360") or				
		("20030068584") or				
		("20030090006") or				
		("20030093173") or				
		("20030151167") or	1			
		("20030155693") or	1			
		("20030205849") or	1			,
		("20030207213")).PN.				
1.79	1	("6630730").PN.	USPAT;	OR	OFF	2005/05/01 20:05
			USOCR		O 1:1:	2005,05,05